


DEVICE AND METHOD FOR LAMP ANNEALING

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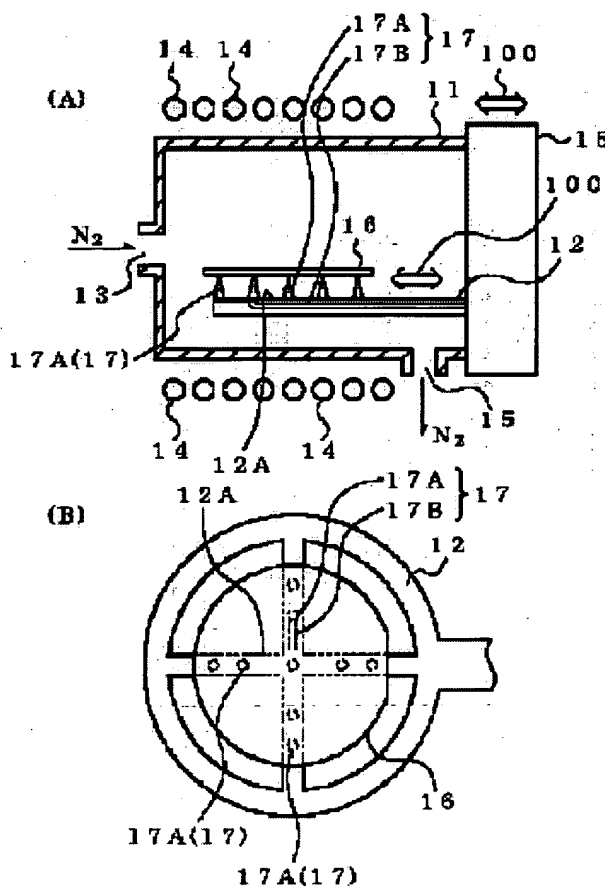
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Abstract of JP11003868

PROBLEM TO BE SOLVED: To prevent variations in the temperature of wafer side of a lamp anneal device during the process of annealing.

SOLUTION: The measured temperature of a wafer 16 at the time of annealing is monitored. The electrical power of a lamp heater 14 for heating wafer is controlled by signals resulting from the monitoring. A thermo couple 17 as a contact temperature sensor for monitoring the measured temperature of the wafer is mounted on a susceptor 12 for supporting the wafer in the treatment chamber or on a base. A plurality of such thermo couples 17 are positioned on the wafer side for monitoring in detail the measured temperature of the wafer side. Each lamp 14 is controlled in accordance with the monitored temperature.



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